

Abstract of the Disclosure:

An IC chip is described that has a number of connecting devices, to which a specific predetermined pin assignment is respectively assigned and the pin assignment is provided more than once. The IC chip can be mounted optionally in a standard wiring, resulting from the pin assignment, or in a mirror-image wiring, mirror-inverted in relation to the standard wiring, likewise resulting from the pin assignment. To be able to produce such a chip at low cost and mount it in a simple manner, it is proposed that at least two groups of metallic bonding pads, which are disposed on the upper side or underside of the IC chip, are provided as the connecting devices and that the first group of bonding pads are assigned the standard wiring or standard pin assignment and at least a second group of bonding pads is assigned the corresponding mirror-image wiring or mirror-image pin assignment.

REL/kf